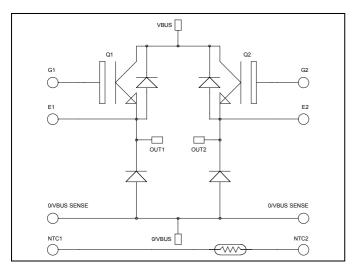


Dual Buck Chopper NPT IGBT Power Module



O/VBUS

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O/VBUS ®

SENSE ®

SENSE (

 $V_{CES} = 1200V$ $I_C = 75A$ @ Tc = 80°C

Application

- AC and DC motor control
- Switched Mode Power Supplies

Features

- Non Punch Through (NPT) Fast IGBT
 - Low voltage drop
 - Low tail current
 - Switching frequency up to 50 kHz
 - Soft recovery parallel diodes
 - Low diode VF
 - Low leakage current
 - RBSOA and SCSOA rated
- Kelvin emitter for easy drive
- Very low stray inductance
 - Symmetrical design
 - Lead frames for power connections
 - Internal thermistor for temperature monitoring
- High level of integration

Benefits

- Outstanding performance at high frequency operation
- Stable temperature behavior
- Very rugged
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Solderable terminals both for power and signal for easy PCB mounting
- Easy paralleling due to positive TC of VCEsat
- Low profile
- RoHS compliant

Absolute maximum ratings

₿ G2

₿ E2

VBUS

<u>Symbol</u>	Parameter		Max ratings	Unit
V_{CES}	Collector - Emitter Breakdown Voltage		1200	V
т	Continuous Collector Current	$T_c = 25^{\circ}C$	100	
1C	I _C Continuous Collector Current		75	A
I_{CM}	Pulsed Collector Current	$T_c = 25^{\circ}C$	150	
$ m V_{GE}$	Gate – Emitter Voltage		±20	V
P_{D}	Maximum Power Dissipation	$T_c = 25$ °C	500	W
RBSOA	Reverse Bias Safe Operating Area	$T_j = 150^{\circ}C$	150A @ 1200V	

OUT2 I

OUT1

NTC2 #

NTC1 8

TAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

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All ratings @ $T_j = 25$ °C unless otherwise specified

Electrical Characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
T	Zero Gate Voltage Collector Current	$V_{GE} = 0V$	$T_j = 25$ °C			250	^
I_{CES}	Zero Gate Voltage Collector Current	$V_{CE} = 1200V$	$T_j = 125$ °C			500	μΑ
V	Collector Emitter saturation Voltage	$V_{GE} = 15V$	$T_j = 25$ °C		3.2	3.7	V
$V_{CE(sat)}$	Collector Ellitter saturation voltage	$I_C = 75A$	$T_j = 125$ °C		3.9		v
$V_{GE(th)}$	Gate Threshold Voltage	$V_{GE} = V_{CE}, I_C =$	2.5 mA	4.5		6.5	V
I_{GES}	Gate – Emitter Leakage Current	$V_{GE} = \pm 20 V, V_{C}$	$V_{GE} = \pm 20V$, $V_{CE} = 0V$			±500	nA

Dynamic Characteristics

Symbol	Characteristic	Test Conditions		Min	Тур	Max	Unit
Cies	Input Capacitance	$V_{GE} = 0V$			5.1		
C_{oes}	Output Capacitance	$V_{CE} = 25V$			0.7		nF
C_{res}	Reverse Transfer Capacitance	f = 1MHz			0.4		
$T_{d(on)}$	Turn-on Delay Time	Inductive Switching (25°C)			120		
T_{r}	Rise Time	$V_{GE} = 15V$			50		na
$T_{d(off)}$	Turn-off Delay Time	$V_{Bus} = 600V$ $I_C = 75A$			310		ns
T_{f}	Fall Time	$R_G = 7.5\Omega$			20		
$T_{d(on)}$	Turn-on Delay Time	Inductive Switch	ning (125°C)		130		
T_{r}	Rise Time	$V_{GE} = 15V$ $V_{Bus} = 600V$ $I_{C} = 75A$			60		
$T_{d(off)}$	Turn-off Delay Time				360		ns
T_{f}	Fall Time	$R_G = 7.5\Omega$			30		
Eon	Turn-on Switching Energy	$V_{GE} = 15V$ $V_{Bus} = 600V$	$T_j = 125$ °C		9		T
E_{off}	Turn-off Switching Energy	$I_C = 75A$ $R_G = 7.5\Omega$	$T_j = 125$ °C		4		mJ

Diode ratings and characteristics

Symbol	Characteristic	Test Conditions	Test Conditions		Typ	Max	Unit
V_{RRM}	Maximum Peak Repetitive Reverse Voltage			1200			V
I_{RM}	Maximum Reverse Leakage Current	V _R =1200V	$T_j = 25$ °C		250		
1 _{RM}	Waximum Reverse Leakage Current		$T_j = 125$ °C			500	μΑ
I_F	DC Forward Current		$Tc = 70^{\circ}C$		100		A
		$I_F = 100A$					
V_{F}	Diode Forward Voltage	$I_F = 200A \\ I_F = 100A \qquad T_j = 125^{\circ}C$		2.3		V	
			$T_{j} = 125^{\circ}C$		1.8		
t	Reverse Recovery Time		$T_j = 25$ °C		420		ns
t _{rr}		$I_F - 100A$	$I_F = 100A$ $V_R = 800V$ $T_j = 125^{\circ}C$ 58	580		113	
Q _{rr}	Reverse Recovery Charge	$di/dt = 200A/\mu s$ $T_j = 25^{\circ}C$ $T_j = 125^{\circ}C$	·	1.2		μС	
			$T_{j} = 125^{\circ}C$		5.3		, r.c



 $Temperature \ sensor \ NTC \ (see \ application \ note \ APT0406 \ on \ www.microsemi.com \ for \ more \ information).$

Symbol	Characteristic	Min	Тур	Max	Unit	
R ₂₅	Resistance @ 25°C		50		kΩ	
${ m B}_{25/85}$	$T_{25} = 298.15 \text{ K}$		3952		K	

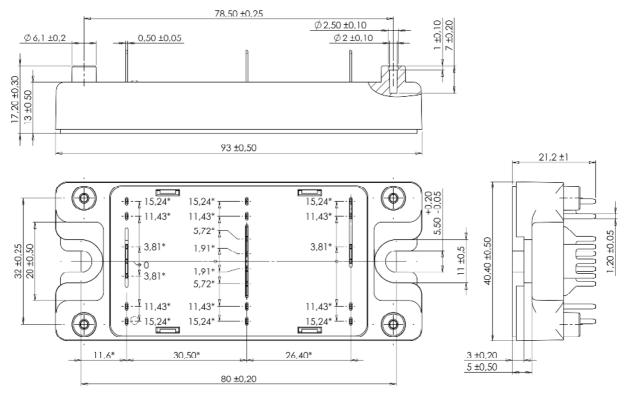
$$R_{T} = \frac{R_{25}}{\exp \left[B_{25/85} \left(\frac{1}{T_{25}} - \frac{1}{T} \right) \right]} \quad \text{T: Thermistor temperature}$$

$$R_{T}: \text{ Thermistor value at T}$$

Thermal and package characteristics

Symbol	Characteristic			Min	Typ	Max	Unit
R_{thJC}	Junction to Case Thermal Resistance		IGBT			0.25	°C/W
IX _{th} JC	Junction to Case Thermal Resistance					0.6	
V_{ISOL}	RMS Isolation Voltage, any terminal to case t =1 min, 50/60Hz			4000			V
T_{J}	Operating junction temperature range		-40		150		
T_{STG}	Storage Temperature Range		-40		125	°C	
$T_{\rm C}$	Operating Case Temperature					100	
Torque	Mounting torque	To heatsink	M5	2.5		4.7	N.m
Wt	Package Weight				160	g	

SP4 Package outline (dimensions in mm)

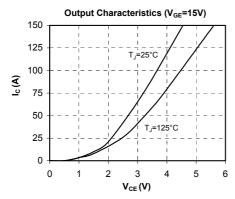


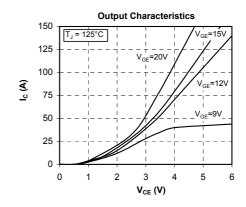
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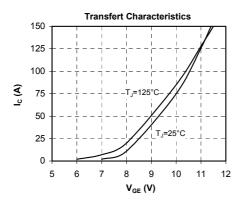
See application note APT0501 - Mounting Instructions for SP4 Power Modules on www.microsemi.com

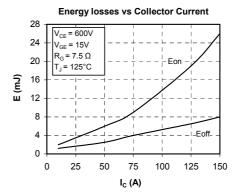


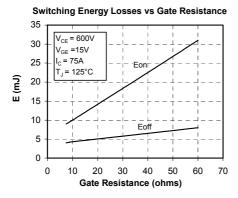
Typical Performance Curve

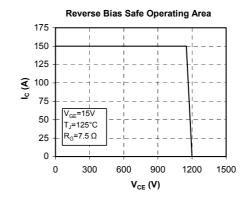


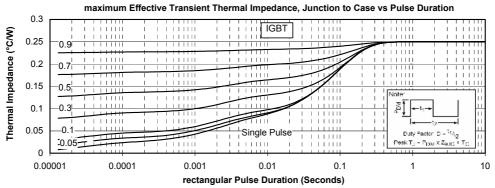




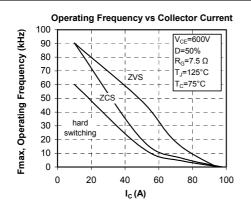


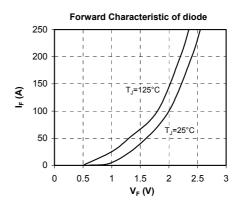


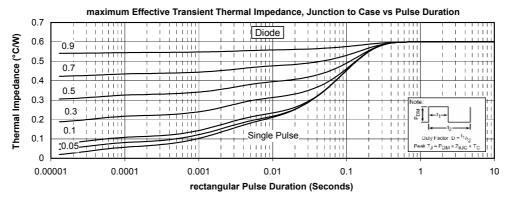












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